

20V N And P-Channel Enhancement Mode MOSFET

Description

The PECN6604 uses advanced trench technology to provide excellent $R_{DS(ON)}$ and low gate charge. The complementary MOSFETs may be used to form a level shifted high side switch, and for a host of other applications.

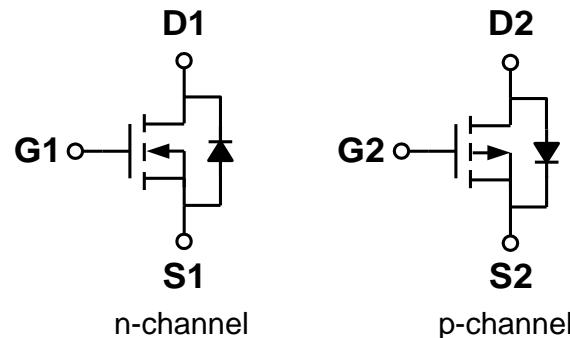
General Features

- ◆ N-channel:
 - $V_{DS} = 20V, ID = 4A$
 - $R_{DS(ON)} = 38m\Omega$ (typical) @ $VGS = 4.5V$
 - $R_{DS(ON)} = 45m\Omega$ (typical) @ $VGS = 2.5V$
- ◆ P-Channel:
 - $V_{DS} = -20V, ID = -3A$
 - $R_{DS(ON)} = 64m\Omega$ (typical) @ $VGS = -4.5V$
 - $R_{DS(ON)} = 82m\Omega$ (typical) @ $VGS = -2.5V$
- ◆ Excellent gate charge $\times R_{DS(ON)}$ product(FOM)
- ◆ Very low on-resistance $R_{DS(ON)}$
- ◆ 150 °C operating temperature
- ◆ Pb-free lead plating
- ◆ 100% UIS tested

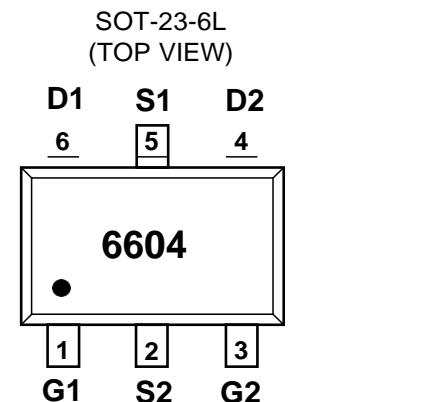
Application

- ◆ DC/DC Converter
- ◆ Ideal for high-frequency switching and synchronous rectification

Schematic diagram



Marking and pin assignment



Package

- ◆ SOT-23-6L



Ordering Information

Part Number	Storage Temperature	Package	Devices Per Reel
PECN6604MR-G	-55°C to +150°C	SOT-23-6L	3000

Absolute Maximum Ratings (TA=25°C unless otherwise noted)

Parameter	Symbol	Limit		Unit
		N	P	
Drain-source voltage	V_{DS}	20	-20	V
Gate-source voltage	V_{GS}	± 12	± 12	V
Maximum power dissipation	P_D	1.1		W
Operating junction Temperature range	T_j	-55—150	-55—150	°C

Drain Current-Continuous (Silicon Limited)	T _A =25°C	I _D	4	-3.2	A
	T _A =75°C		3	-2.6	
Pulsed Drain Current (Package Limited)	I _{DM}		16	-12.8	A
Junction and Storage Temperature Range	T _J , T _{STG}	-55—150		°C	

N-Channel Electrical Characteristics (T_J=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
OFF Characteristics						
Drain-source breakdown voltage	BV _{DSS}	V _{GS} =0V, I _D =250μA	20	-	-	V
Zero gate voltage drain current	I _{DSS}	V _{DS} =20V, V _{GS} =0V	-	-	1	μA
Gate-body leakage	I _{GSS}	V _{DS} =0V, V _{GS} =±12V	-	-	±100	nA
ON Characteristics						
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	0.5	0.75	1.2	V
Drain-source on-state resistance	R _{DS(ON)}	V _{GS} =4.5V, I _D =3A	-	38	48	mΩ
		V _{GS} =2.5V, I _D =2A		45	55	
Forward transconductance	g _{fs}	V _{GS} =5V, I _D =3A	-	5	-	S
Dynamic Characteristics						
Input capacitance	C _{ISS}	V _{DS} =10V, V _{GS} =0V f=1.0MHz	-	240	-	pF
Output capacitance	C _{OSS}		-	45	-	
Reverse transfer capacitance	C _{RSS}		-	23	-	
Switching Characteristics						
Turn-on delay time	t _{D(ON)}	V _{DD} =10V R _L =3.3 ohm V _{GEN} =4.5V R _{GEN} =6ohm	-	2.3	-	ns
Rise time	tr		-	3.1	-	
Turn-off delay time	t _{D(OFF)}		-	21	-	
Fall time	tf		-	2.6	-	
Total gate charge	Q _g	V _{DS} =10V I _D =3A V _{GS} =4.5V	-	2.7	-	nC
Gate-source charge	Q _{gs}		-	0.4	-	
Gate-drain charge	Q _{gd}		-	0.5	-	
DRAIN-SOURCE DIODE CHARACTERISTICS						
Diode forward voltage	V _{SD}	V _{GS} =0V, I _s =3A	-	0.76	1.16	V

Thermal Characteristics

Thermal Resistance junction-to ambient	R _{th JA}	100	°C/W
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N-Channel: Typical Electrical And Thermal Characteristics

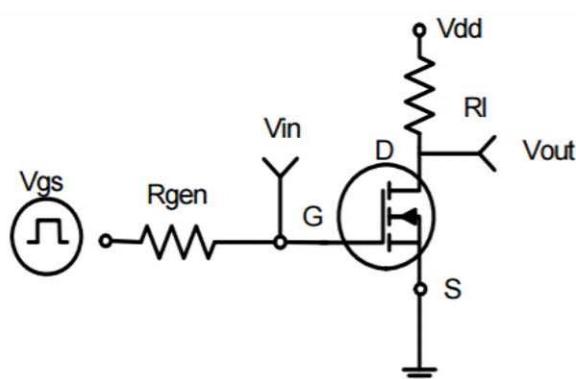


Figure 1:Switching Test Circuit

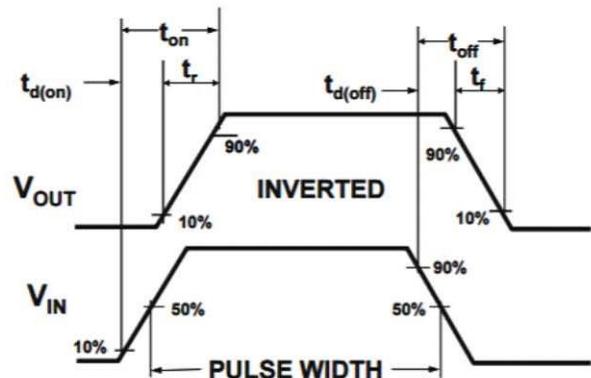


Figure 2:Switching Waveforms

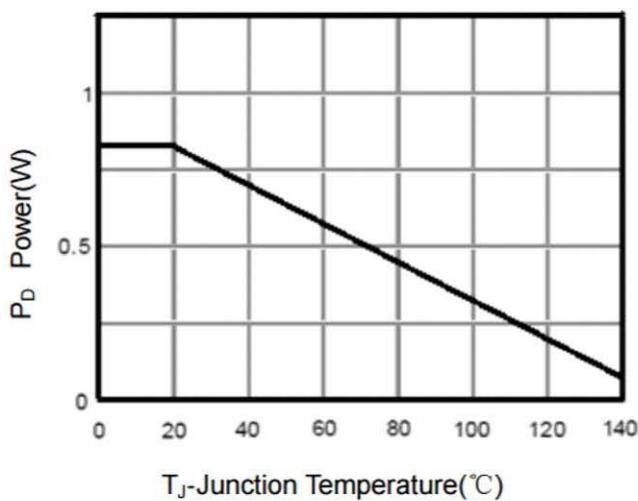


Figure 3 Power Dissipation

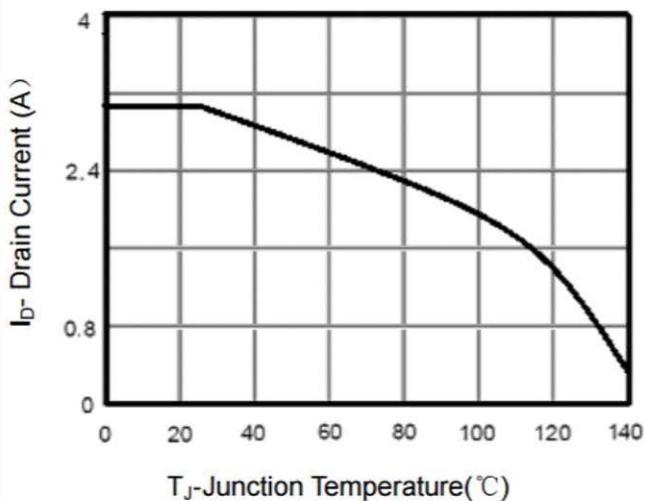


Figure 4 Drain Current

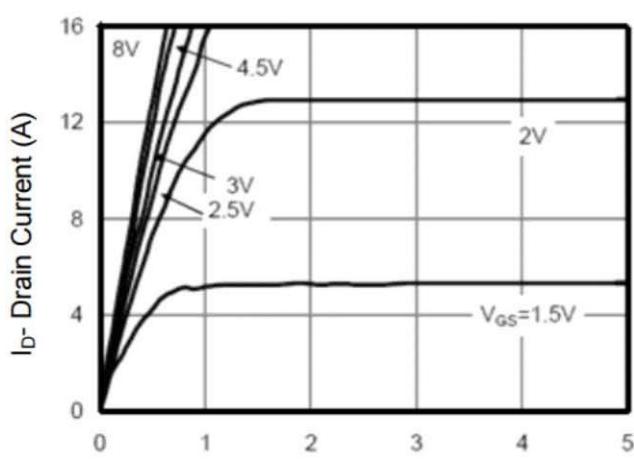


Figure 5 Output Characteristics

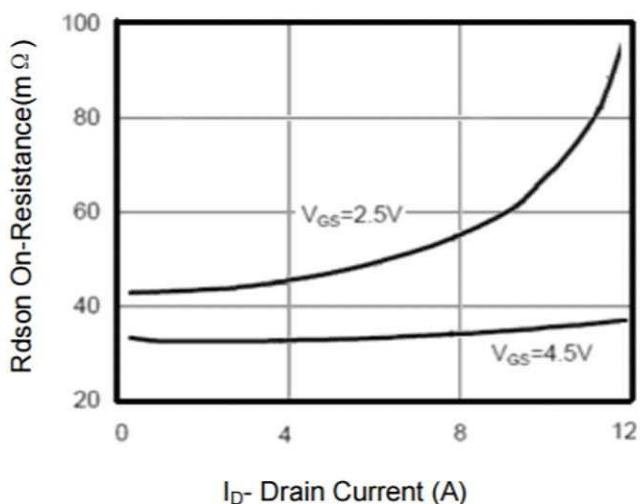


Figure 6 Drain-Source On-Resistance

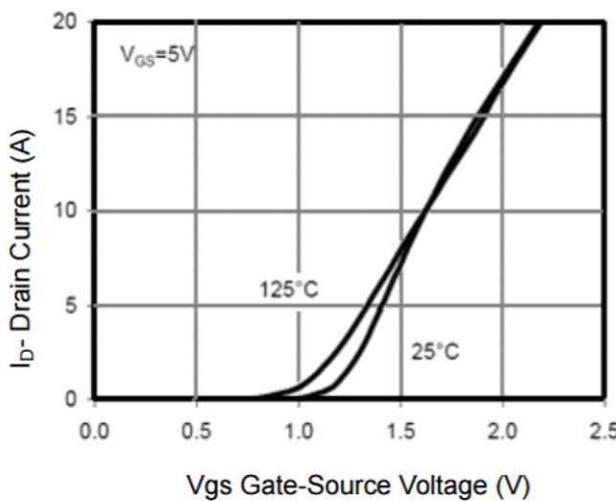


Figure 7 Transfer Characteristics

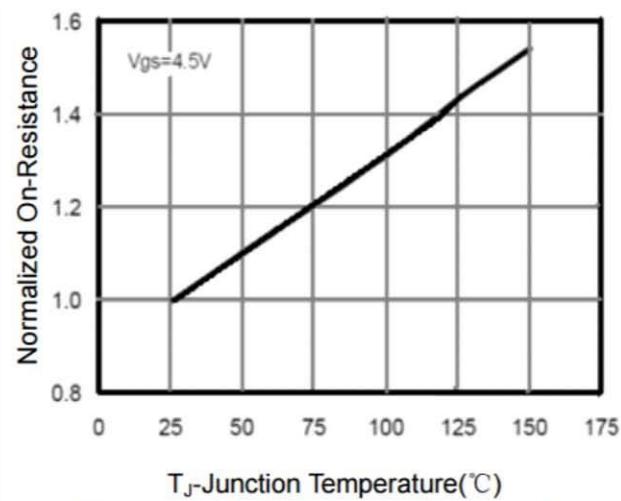


Figure 8 Drain-Source On-Resistance

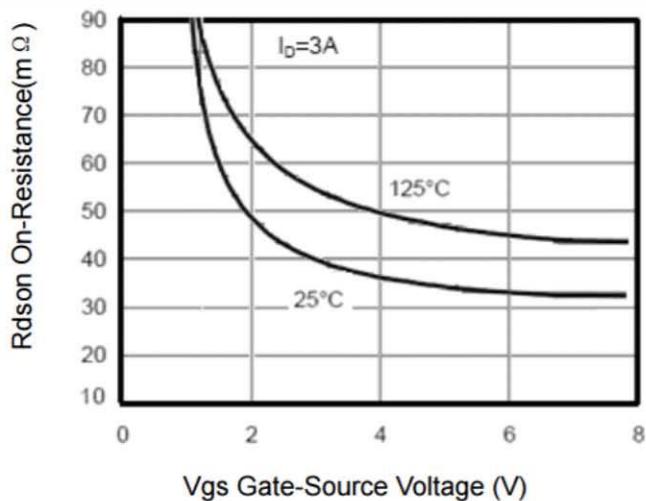


Figure 9 R_{DSON} vs V_{GS}

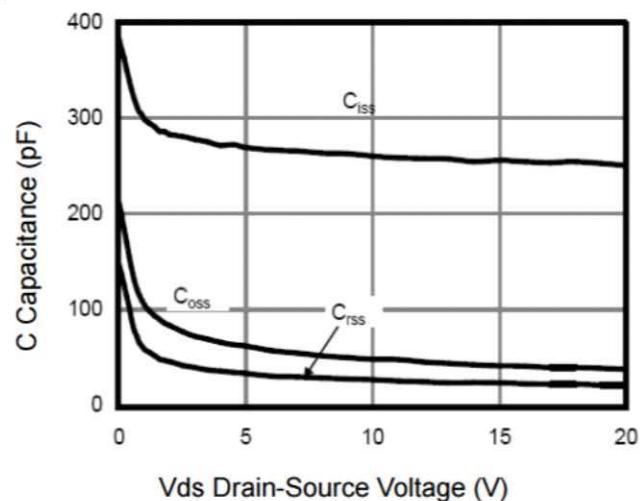


Figure 10 Capacitance vs V_{DS}

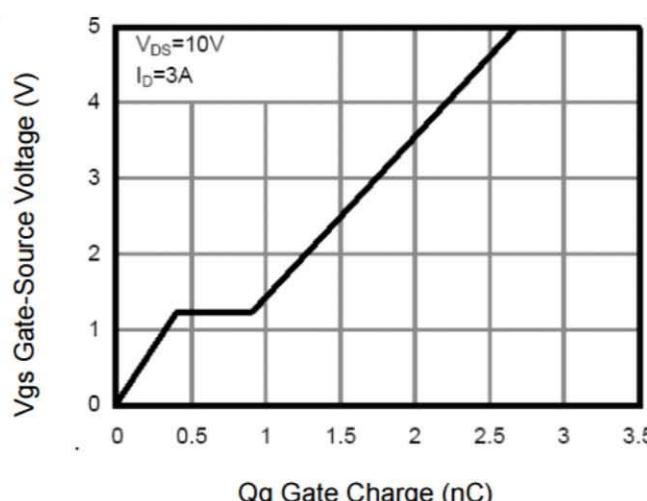


Figure 11 Gate Charge

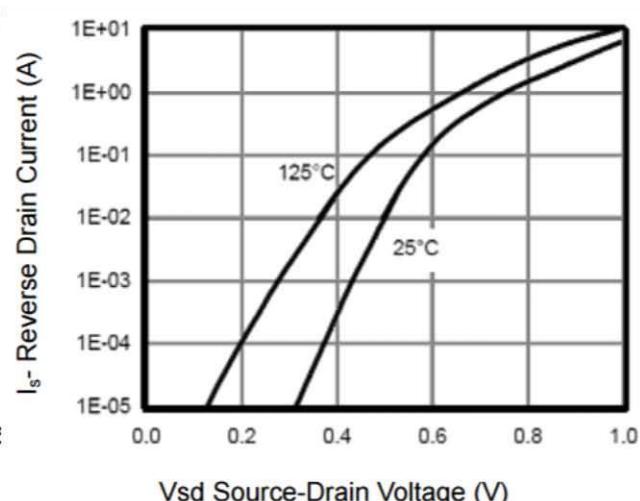
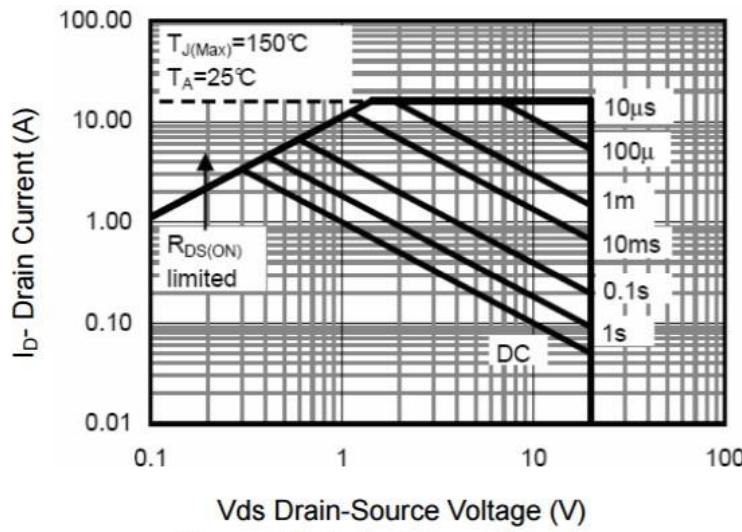
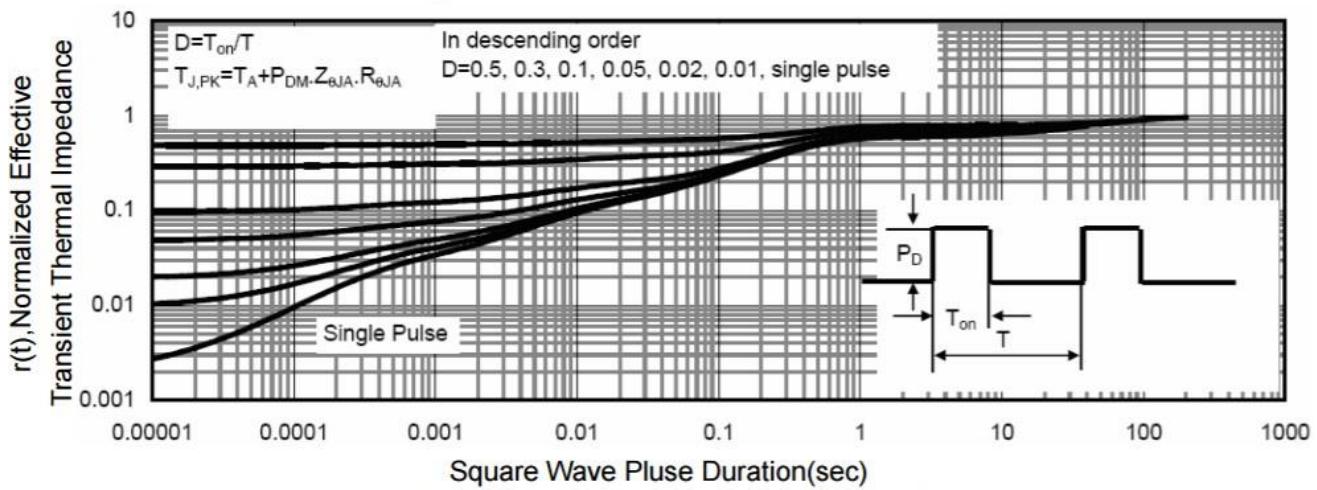


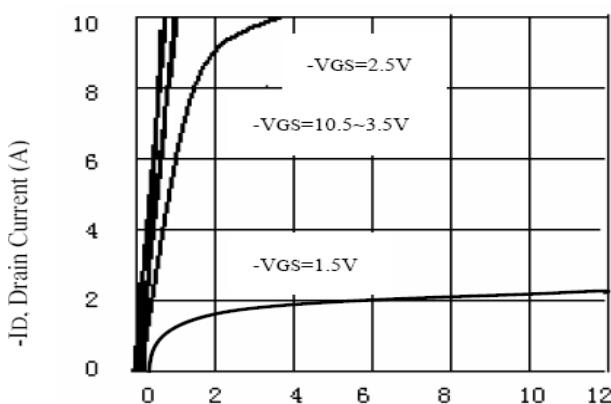
Figure 12 Source- Drain Diode Forward

**Figure 13 Safe Operation Area****Figure 14 Normalized Maximum Transient Thermal Impedance**

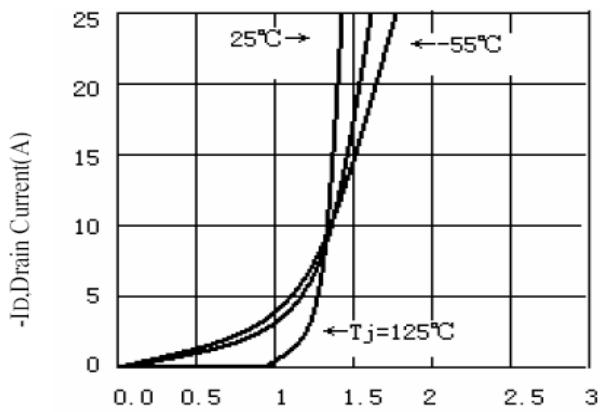
P-Channel Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
OFF Characteristics						
Drain-source breakdown voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=-250\mu\text{A}$	-20	-	-	V
Zero gate voltage drain current	I_{DSS}	$V_{\text{DS}}=-20\text{V}, V_{\text{GS}}=0\text{V}$	-	-	-1	μA
Gate-body leakage	I_{GSS}	$V_{\text{DS}}=0\text{V}, V_{\text{GS}}=\pm 12\text{V}$	-	-	± 100	nA
ON Characteristics						
Gate threshold voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=-250\mu\text{A}$	-0.4	-0.65	-1.2	V
Drain-source on-state resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=-4.5\text{V}, I_{\text{D}}=-3\text{A}$	-	64	80	$\text{m}\Omega$
		$V_{\text{GS}}=-2.5\text{V}, I_{\text{D}}=-2\text{A}$	-	82	120	
Forward transconductance	g_{fs}	$V_{\text{GS}}=-5\text{V}, I_{\text{D}}=-5\text{A}$	-	5	-	S
Dynamic Characteristics						
Input capacitance	C_{ISS}	$V_{\text{DS}}=-10\text{V}, V_{\text{GS}}=0\text{V}$ $f=1.0\text{MHz}$	-	561	-	pF
Output capacitance	C_{OSS}		-	61	-	
Reverse transfer capacitance	C_{RSS}		-	52	-	
Switching Characteristics						
Turn-on delay time	$t_{\text{D}(\text{ON})}$	$V_{\text{DD}}=-10\text{V}$ $I_{\text{D}}=-2.8\text{A}$ $V_{\text{GEN}}=-4.5\text{V}$ $R_{\text{L}}=10\text{ohm}$ $R_{\text{GEN}}=60\text{ohm}$	-	12.5	-	ns
Rise time	t_{r}		-	6.6	-	
Turn-off delay time	$t_{\text{D}(\text{OFF})}$		-	113	-	
Fall time	t_{f}		-	46.6	-	
Total gate charge	Q_{g}	$V_{\text{DS}}=-10\text{V}, I_{\text{D}}=-3\text{A}$ $V_{\text{GS}}=-4.5\text{V}$	-	6.1	-	nC
Gate-source charge	Q_{gs}		-	1.7	-	
Gate-drain charge	Q_{gd}		-	1.2	-	
DRAIN-SOURCE DIODE CHARACTERISTICS						
Diode forward voltage	V_{SD}	$V_{\text{GS}}=0\text{V}, I_{\text{S}}=-1.25\text{A}$	-	-0.81	-1.2	V

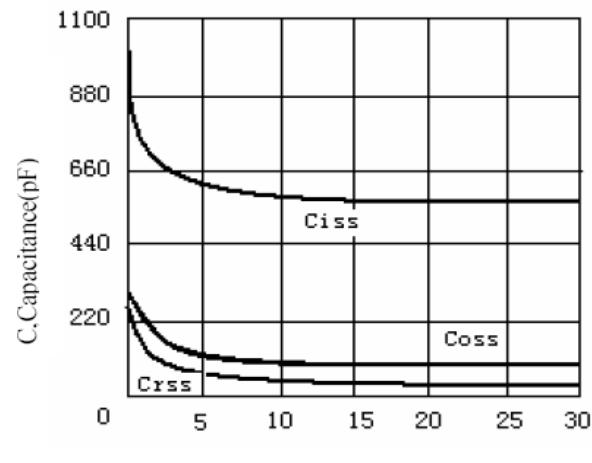
P-Channel: Typical Electrical And Thermal Characteristics



- V_{DS} , Drain-to-Source Voltage (V)
Figure 1. Output Characteristics



- V_{GS} , Gate-to-source Voltage (V)
Figure 2. Transfer Characteristics



- V_{GS} , Drain-to Source Voltage
Figure3. Capacitance

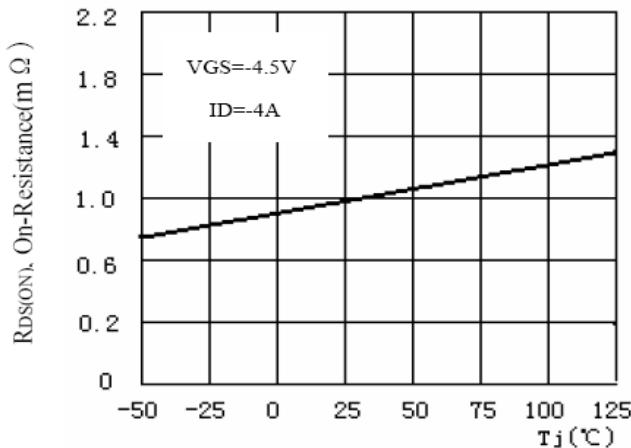
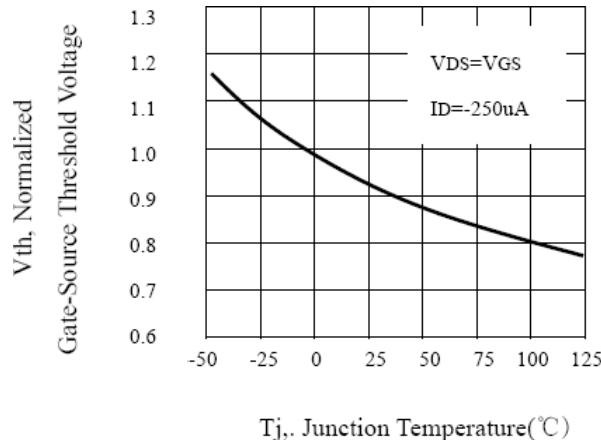
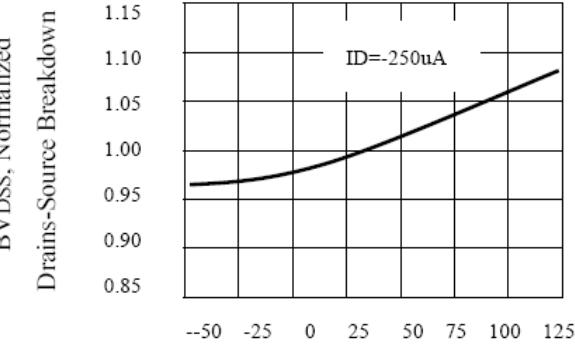


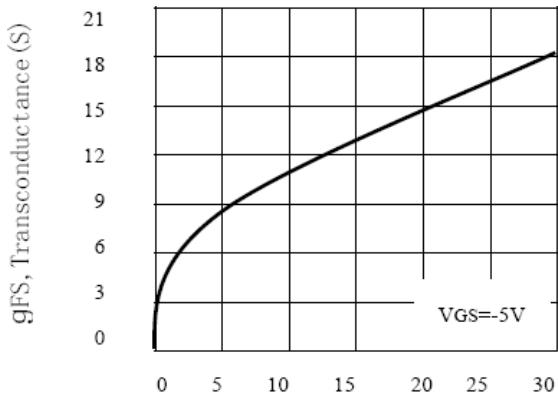
Figure4. On-Resistance Variation with Temperature



$V_{DS} = V_{GS}$
 $ID = -250\mu\text{A}$
T_j, Junction Temperature (°C)
Figure5.Gate Threshold Variation With Temperature

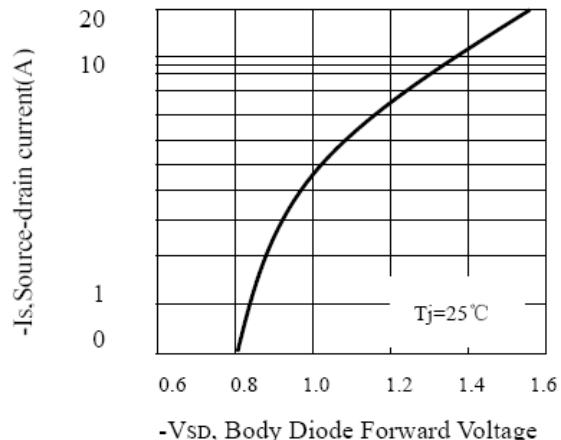


$ID = -250\mu\text{A}$
T_j, Junction Temperature (°C)
Figure6.Breakdown Voltage Variation With Temperature



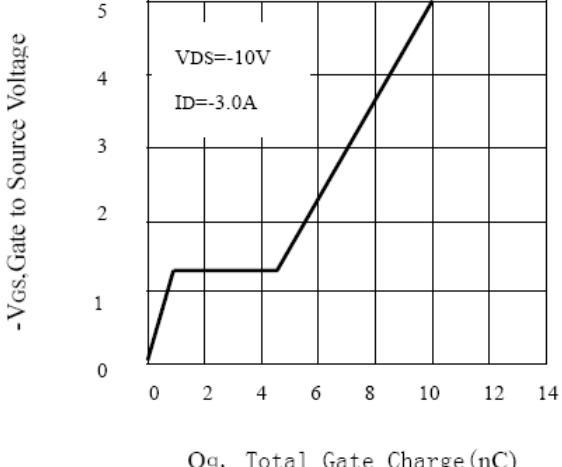
- I_{DS} , Drain-Source Current (A)

Figure7. Transconductance Variation
With Drain Current



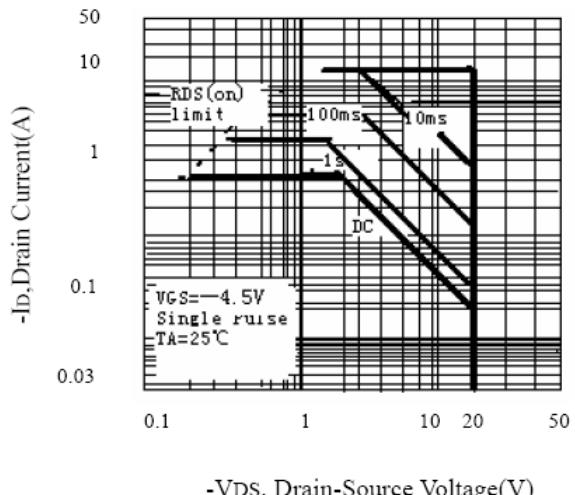
- V_{SD} , Body Diode Forward Voltage

Figure8. Body Diode Forward Voltage
Variation with Source Current



Q_g , Total Gate Charge (nC)

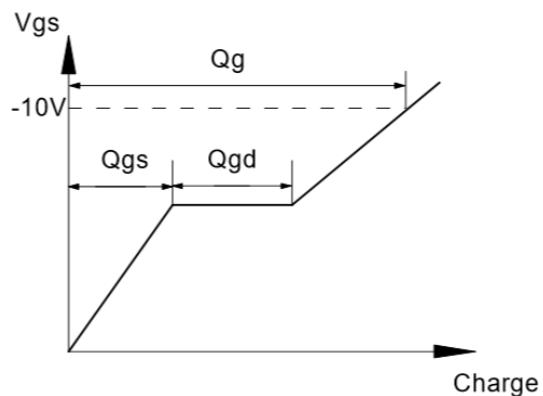
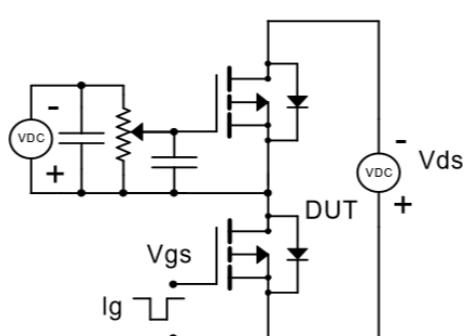
Figure9. Gate Charge



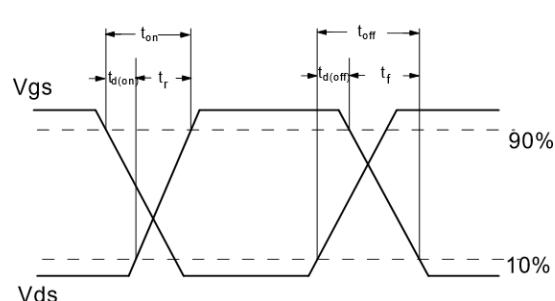
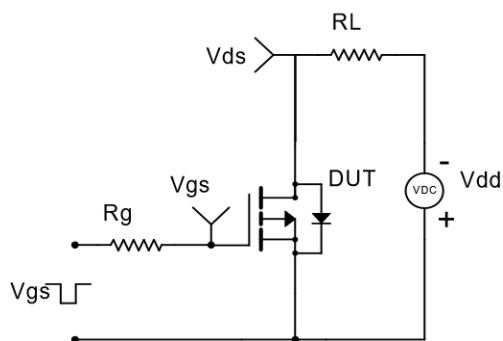
- V_{DS} , Drain-Source Voltage(V)

Figure10. Maximum Safe Operating Area

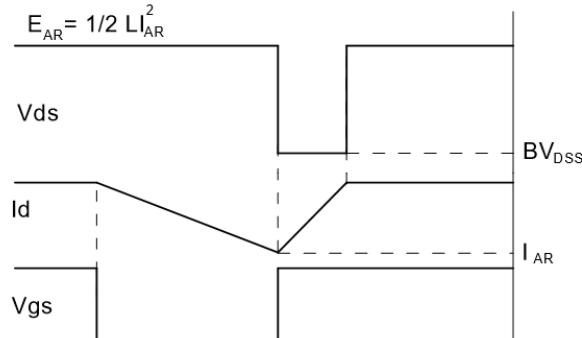
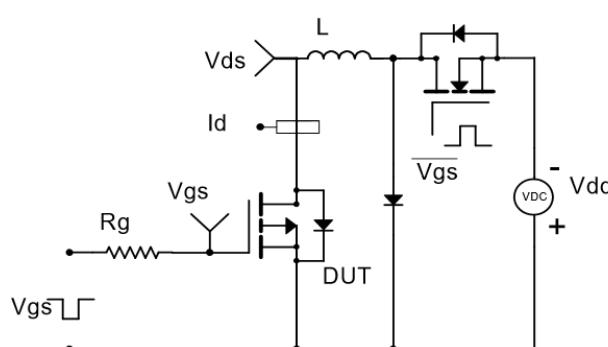
Gate Charge Test Circuit & Waveform



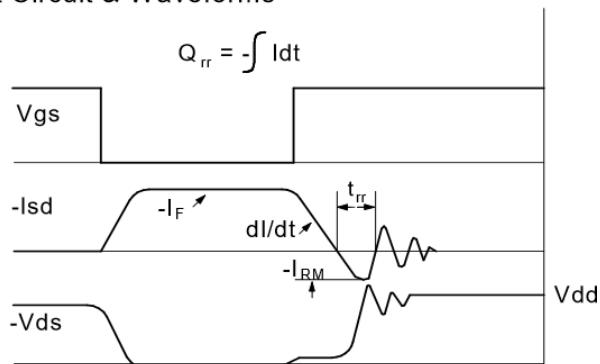
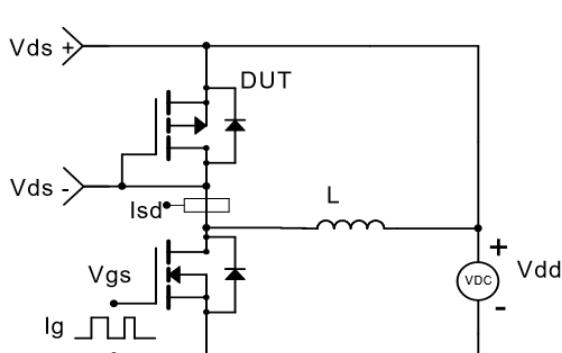
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

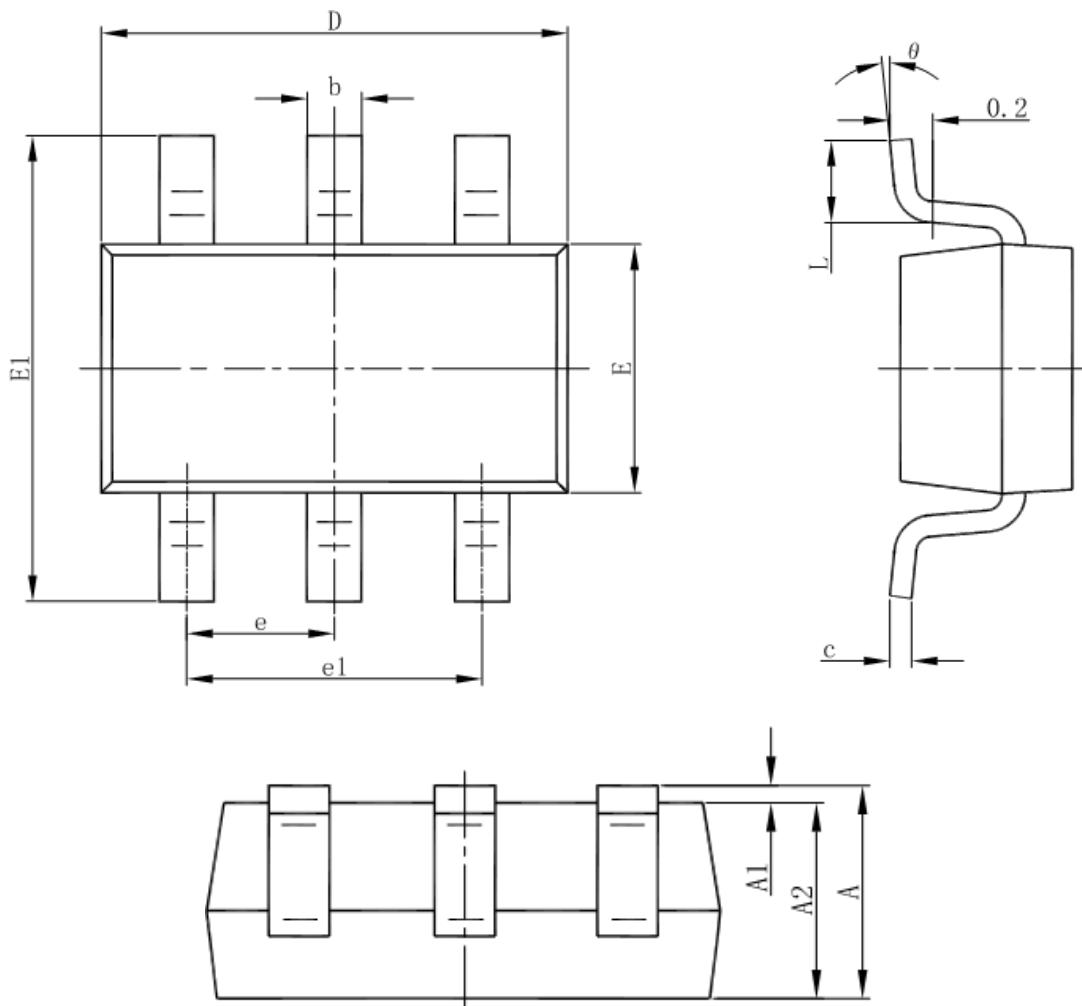


Diode Recovery Test Circuit & Waveforms



Package Information

- SOT-23-6L



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°